

74HC14; 74HCT14

Hex inverting Schmitt trigger

Rev. 6 — 19 September 2012

Product data sheet

1. General description

The 74HC14; 74HCT14 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7A.

The 74HC14; 74HCT14 provides six inverting buffers with Schmitt-trigger action. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

2. Features and benefits

- Low-power dissipation
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Applications

- Wave and pulse shapers
- Astable multivibrators
- Monostable multivibrators



4. Ordering information

Table 1. Ordering information

| Type number | Package | | | Version |
|-----------------------|-------------------|----------|--|----------|
| | Temperature range | Name | Description | |
| 74HC14N 74HCT14N | -40 °C to +125 °C | DIP14 | plastic dual in-line package; 14 leads (300 mil) | SOT27-1 |
| 74HC14D 74HCT14D | -40 °C to +125 °C | SO14 | plastic small outline package; 14 leads; body width 3.9 mm | SOT108-1 |
| 74HC14DB 74HCT14DB | -40 °C to +125 °C | SSOP14 | plastic shrink small outline package; 14 leads; body width 5.3 mm | SOT337-1 |
| 74HC14PW 74HCT14PW | -40 °C to +125 °C | TSSOP14 | plastic thin shrink small outline package; 14 leads; body width 4.4 mm | SOT402-1 |
| 74HC14BQ 74HCT14BQ | -40 °C to +125 °C | DHVQFN14 | plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm | SOT762-1 |

5. Functional diagram

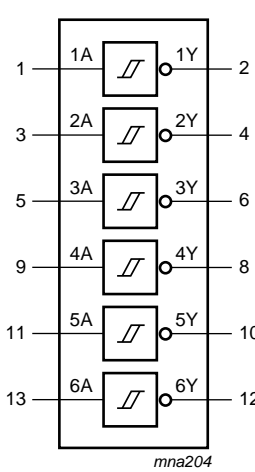


Fig 1. Logic symbol

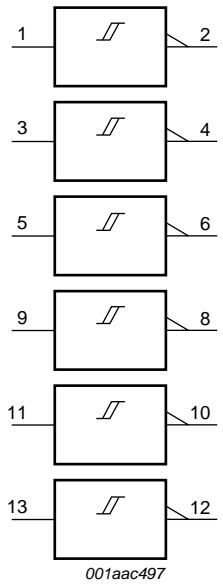


Fig 2. IEC logic symbol

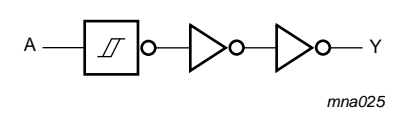


Fig 3. Logic diagram (one Schmitt trigger)

6. Pinning information

6.1 Pinning

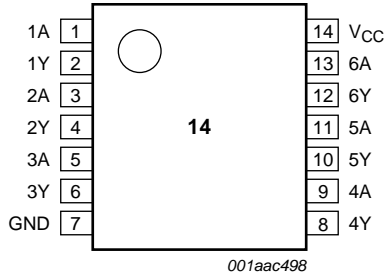
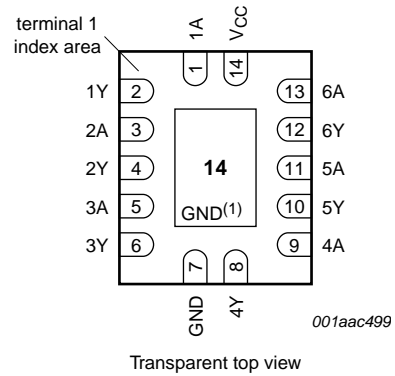


Fig 4. Pin configuration DIP14, SO14 and (T)SSOP14



- (1) The die substrate is attached to this pad using conductive die attach material. It cannot be used as a supply pin or input.

Fig 5. Pin configuration DHVQFN14

6.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|-----------------|--------------------|----------------|
| 1A to 6A | 1, 3, 5, 9, 11, 13 | data input 1 |
| 1Y to 6Y | 2, 4, 6, 8, 10, 12 | data output 1 |
| GND | 7 | ground (0 V) |
| V _{CC} | 14 | supply voltage |

7. Functional description

Table 3. Function table^[1]

| Input | Output |
|-------|--------|
| nA | nY |
| L | H |
| H | L |

[1] H = HIGH voltage level;
L = LOW voltage level.

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|---------------------------------------|---|-------|------|------|
| V _{CC} | supply voltage | | -0.5 | +7 | V |
| I _{IK} | input clamping current | V _I < -0.5 V or V _I > V _{CC} + 0.5 V | [1] - | ±20 | mA |
| I _{OK} | output clamping current | V _O < -0.5 V or V _O > V _{CC} + 0.5 V | [1] - | ±20 | mA |
| I _O | output current | -0.5 V < V _O < V _{CC} + 0.5 V | - | ±25 | mA |
| I _{CC} | supply current | | - | 50 | mA |
| I _{GND} | ground current | | -50 | - | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _{tot} | total power dissipation | | [2] | | |
| | DIP14 package | | - | 750 | mW |
| | SO14, (T)SSOP14 and DHVQFN14 packages | | - | 500 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP14 package: P_{tot} derates linearly with 12 mW/K above 70 °C.
 For SO14 package: P_{tot} derates linearly with 8 mW/K above 70 °C.
 For (T)SSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.
 For DHVQFN14 packages: P_{tot} derates linearly with 4.5 mW/K above 60 °C.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

| Symbol | Parameter | Conditions | 74HC14 | | | 74HCT14 | | | Unit |
|------------------|---------------------|------------|--------|-----|-----------------|---------|-----|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 6.0 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| T _{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |

10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | T _{amb} = 25 °C | | | T _{amb} = -40 °C to +85 °C | | T _{amb} = -40 °C to +125 °C | | Unit |
|------------------|---------------------------|---|--------------------------|------|------|-------------------------------------|------|--------------------------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC14 | | | | | | | | | | |
| V _{OH} | HIGH-level output voltage | V _I = V _{T+} or V _{T-} | | | | | | | | |
| | | I _O = -20 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -20 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -20 μA; V _{CC} = 6.0 V | 5.9 | 6.0 | - | 5.9 | - | 5.9 | - | V |
| | | I _O = -4.0 mA; V _{CC} = 4.5 V | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| | | I _O = -5.2 mA; V _{CC} = 6.0 V | 5.48 | 5.81 | - | 5.34 | - | 5.2 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{T+} or V _{T-} | | | | | | | | |
| | | I _O = 20 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 6.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 4.5 V | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| | | I _O = 5.2 mA; V _{CC} = 6.0 V | - | 0.16 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V | - | - | 2.0 | - | 20 | - | 40 | μA |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |
| 74HCT14 | | | | | | | | | | |
| V _{OH} | HIGH-level output voltage | V _I = V _{T+} or V _{T-} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = -20 μA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -4.0 mA | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{T+} or V _{T-} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 20 μA; | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 5.5 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 2.0 | - | 20 | - | 40 | μA |
| ΔI _{CC} | additional supply current | per input pin; V _I = V _{CC} - 2.1 V; other pins at V _{CC} or GND; I _O = 0 A; V _{CC} = 4.5 V to 5.5 V | - | 30 | 108 | - | 135 | - | 147 | μA |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |

11. Dynamic characteristics

Table 7. Dynamic characteristics

$GND = 0\text{ V}$; $C_L = 50\text{ pF}$; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | $T_{amb} = 25\text{ °C}$ | | | $T_{amb} = -40\text{ °C to }+125\text{ °C}$ | | Unit |
|----------------|-------------------------------|--|--------------------------|-----|-----|---|--------------|------|
| | | | Min | Typ | Max | Max (85 °C) | Max (125 °C) | |
| 74HC14 | | | | | | | | |
| t_{pd} | propagation delay | nA to nY; see Figure 6 [1] | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 41 | 125 | 155 | 190 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 15 | 25 | 31 | 38 | ns |
| | | $V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$ | - | 12 | - | - | - | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 12 | 21 | 26 | 32 | ns |
| t_t | transition time | see Figure 6 [2] | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 19 | 75 | 95 | 110 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 7 | 15 | 19 | 22 | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 6 | 13 | 15 | 19 | ns |
| C_{PD} | power dissipation capacitance | per package; $V_I = GND\text{ to }V_{CC}$ [3] | - | 7 | - | - | - | pF |
| 74HCT14 | | | | | | | | |
| t_{pd} | propagation delay | nA to nY; see Figure 6 [1] | | | | | | |
| | | $V_{CC} = 4.5\text{ V}$ | - | 20 | 34 | 43 | 51 | ns |
| | | $V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$ | - | 17 | - | - | - | ns |
| t_t | transition time | $V_{CC} = 4.5\text{ V}$; see Figure 6 [2] | - | 7 | 15 | 19 | 22 | ns |
| C_{PD} | power dissipation capacitance | per package; $V_I = GND\text{ to }V_{CC} - 1.5\text{ V}$ [3] | - | 8 | - | - | - | pF |

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .

[2] t_t is the same as t_{THL} and t_{TLH} .

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

12. Waveforms

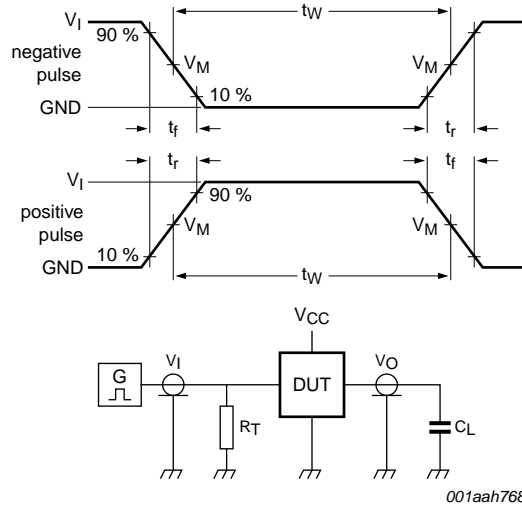


Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Input to output propagation delays

Table 8. Measurement points

| Type | Input | Output | | |
|---------|-------------|-------------|-------------|-------------|
| | V_M | V_M | V_X | V_Y |
| 74HC14 | $0.5V_{CC}$ | $0.5V_{CC}$ | $0.1V_{CC}$ | $0.9V_{CC}$ |
| 74HCT14 | 1.3 V | 1.3 V | $0.1V_{CC}$ | $0.9V_{CC}$ |



Test data is given in [Table 9](#).
 Definitions test circuit:
 R_T = termination resistance should be equal to output impedance Z_o of the pulse generator.
 C_L = load capacitance including jig and probe capacitance.

Fig 7. Load circuitry for measuring switching times

Table 9. Test data

| Type | Input | | Load | Test |
|---------|----------|------------|--------------|--------------------|
| | V_I | t_r, t_f | C_L | |
| 74HC14 | V_{CC} | 6.0 ns | 15 pF, 50 pF | t_{PLH}, t_{PHL} |
| 74HCT14 | 3.0 V | 6.0 ns | 15 pF, 50 pF | t_{PLH}, t_{PHL} |

13. Transfer characteristics

Table 10. Transfer characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); see Figure 8 and Figure 9.

| Symbol | Parameter | Conditions | $T_{amb} = 25\text{ }^\circ\text{C}$ | | | $T_{amb} = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$ | | $T_{amb} = -40\text{ }^\circ\text{C}$ to $+125\text{ }^\circ\text{C}$ | | Unit |
|----------------|----------------------------------|-------------------------|--------------------------------------|------|------|---|------|--|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC14 | | | | | | | | | | |
| V_{T+} | positive-going threshold voltage | $V_{CC} = 2.0\text{ V}$ | 0.7 | 1.18 | 1.5 | 0.7 | 1.5 | 0.7 | 1.5 | V |
| | | $V_{CC} = 4.5\text{ V}$ | 1.7 | 2.38 | 3.15 | 1.7 | 3.15 | 1.7 | 3.15 | V |
| | | $V_{CC} = 6.0\text{ V}$ | 2.1 | 3.14 | 4.2 | 2.1 | 4.2 | 2.1 | 4.2 | V |
| V_{T-} | negative-going threshold voltage | $V_{CC} = 2.0\text{ V}$ | 0.3 | 0.52 | 0.9 | 0.3 | 0.9 | 0.3 | 0.9 | V |
| | | $V_{CC} = 4.5\text{ V}$ | 0.9 | 1.4 | 2.0 | 0.9 | 2.0 | 0.9 | 2.0 | V |
| | | $V_{CC} = 6.0\text{ V}$ | 1.2 | 1.89 | 2.6 | 1.2 | 2.6 | 1.2 | 2.6 | V |
| V_H | hysteresis voltage | $V_{CC} = 2.0\text{ V}$ | 0.2 | 0.66 | 1.0 | 0.2 | 1.0 | 0.2 | 1.0 | V |
| | | $V_{CC} = 4.5\text{ V}$ | 0.4 | 0.98 | 1.4 | 0.4 | 1.4 | 0.4 | 1.4 | V |
| | | $V_{CC} = 6.0\text{ V}$ | 0.6 | 1.25 | 1.6 | 0.6 | 1.6 | 0.6 | 1.6 | V |
| 74HCT14 | | | | | | | | | | |
| V_{T+} | positive-going threshold voltage | $V_{CC} = 4.5\text{ V}$ | 1.2 | 1.41 | 1.9 | 1.2 | 1.9 | 1.2 | 1.9 | V |
| | | $V_{CC} = 5.5\text{ V}$ | 1.4 | 1.59 | 2.1 | 1.4 | 2.1 | 1.4 | 2.1 | V |
| V_{T-} | negative-going threshold voltage | $V_{CC} = 4.5\text{ V}$ | 0.5 | 0.85 | 1.2 | 0.5 | 1.2 | 0.5 | 1.2 | V |
| | | $V_{CC} = 5.5\text{ V}$ | 0.6 | 0.99 | 1.4 | 0.6 | 1.4 | 0.6 | 1.4 | V |
| V_H | hysteresis voltage | $V_{CC} = 4.5\text{ V}$ | 0.4 | 0.56 | - | 0.4 | - | 0.4 | - | V |
| | | $V_{CC} = 5.5\text{ V}$ | 0.4 | 0.6 | - | 0.4 | - | 0.4 | - | V |

14. Transfer characteristics waveforms

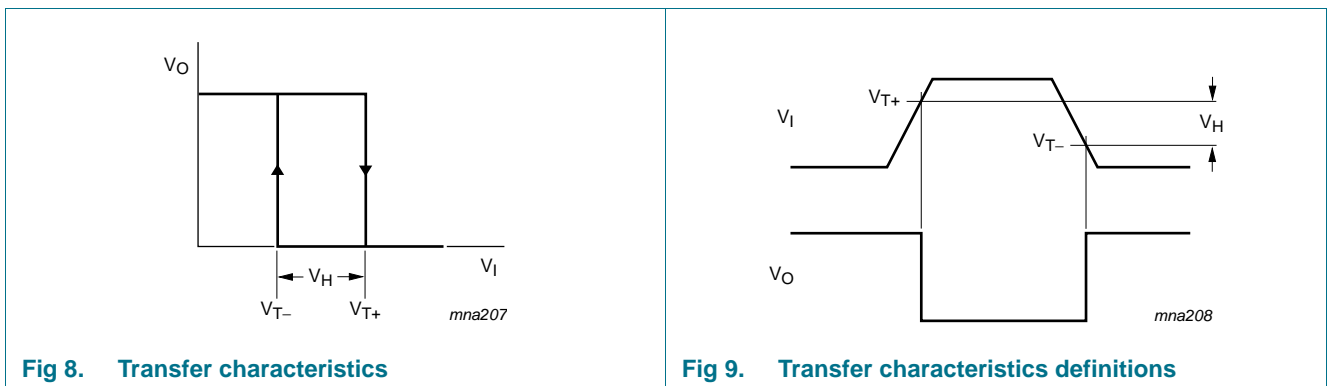
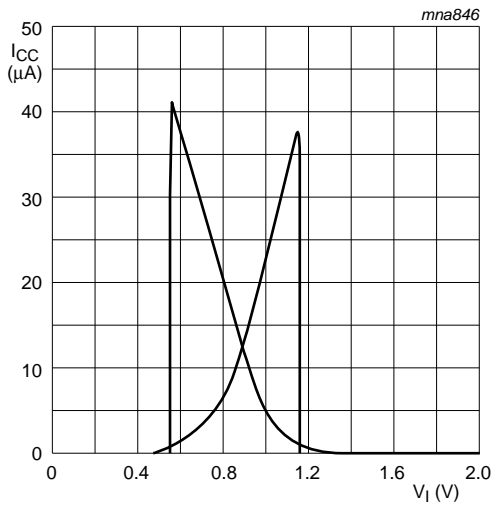
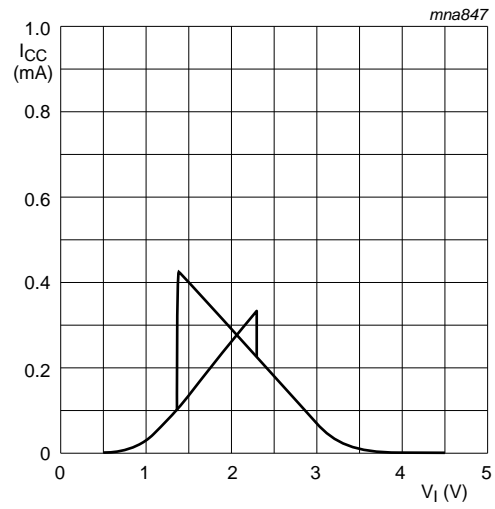


Fig 8. Transfer characteristics

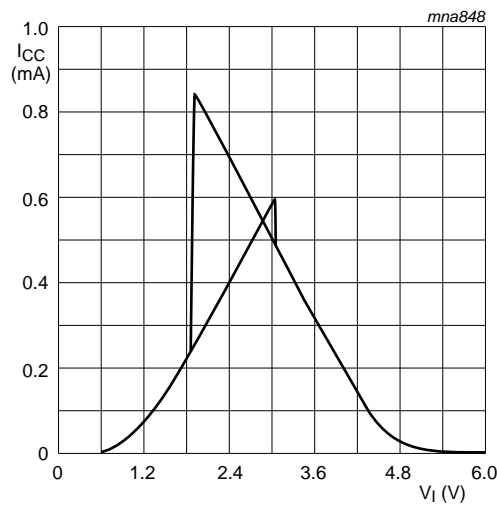
Fig 9. Transfer characteristics definitions



a. $V_{CC} = 2.0\text{ V}$

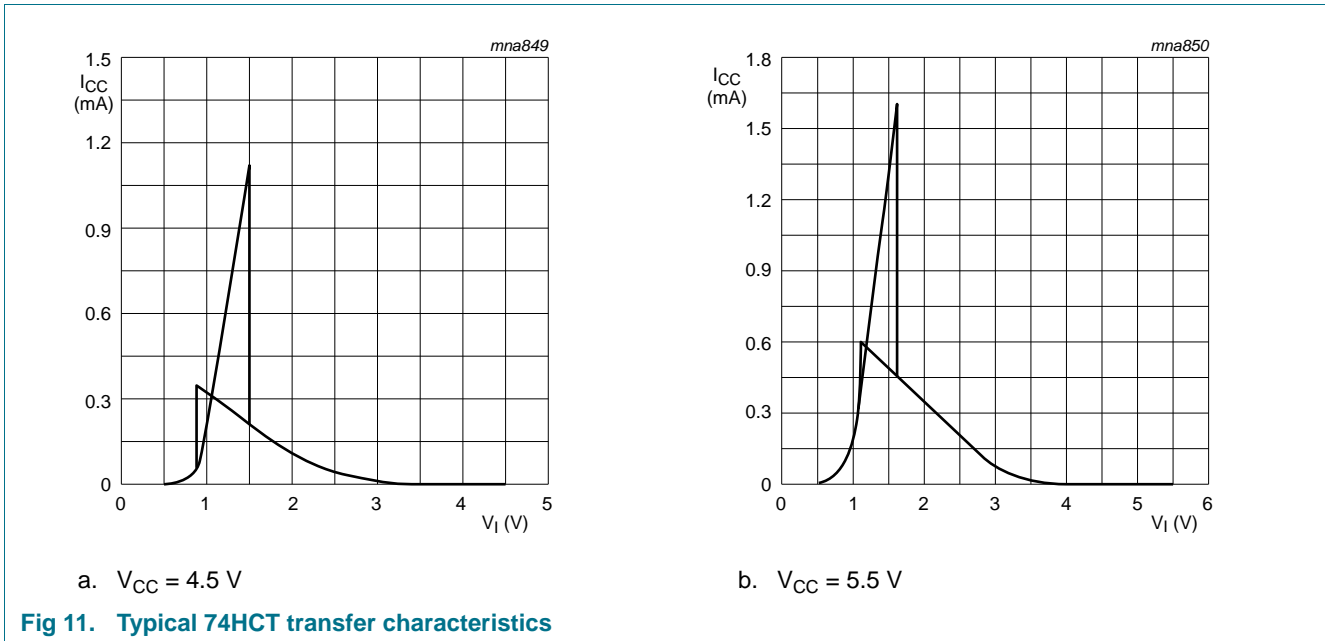


b. $V_{CC} = 4.5\text{ V}$



c. $V_{CC} = 6.0\text{ V}$

Fig 10. Typical 74HC transfer characteristics



15. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

$$P_{\text{add}} = f_i \times (t_r \times \Delta I_{\text{CC(AV)}} + t_f \times \Delta I_{\text{CC(AV)}}) \times V_{\text{CC}} \text{ where:}$$

P_{add} = additional power dissipation (μW);

f_i = input frequency (MHz);

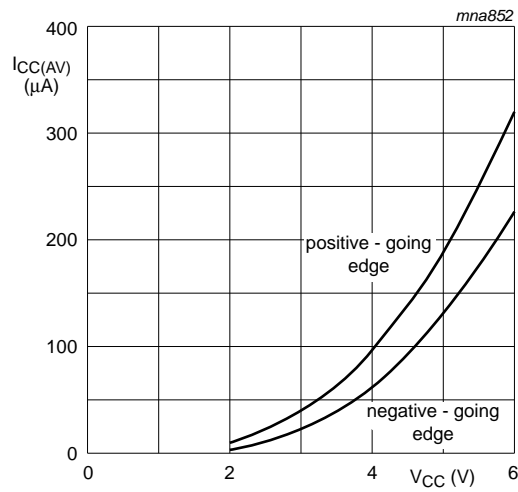
t_r = rise time (ns); 10 % to 90 %;

t_f = fall time (ns); 90 % to 10 %;

$\Delta I_{\text{CC(AV)}}$ = average additional supply current (μA).

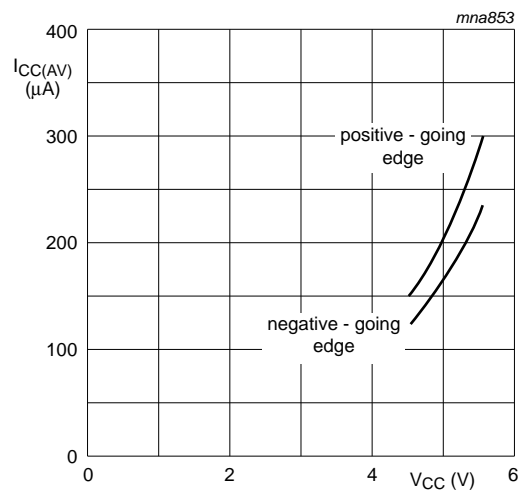
Average $\Delta I_{\text{CC(AV)}}$ differs with positive or negative input transitions, as shown in [Figure 12](#) and [Figure 13](#).

An example of a relaxation circuit using the 74HC14; 74HCT14 is shown in [Figure 14](#).



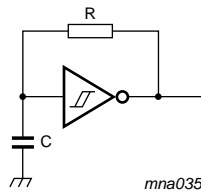
- (1) Positive-going edge.
- (2) Negative-going edge.

Fig 12. Average additional supply current as a function of V_{CC} for 74HC14; linear change of V_I between 0.1V_{CC} to 0.9V_{CC}.



- (1) Positive-going edge.
- (2) Negative-going edge.

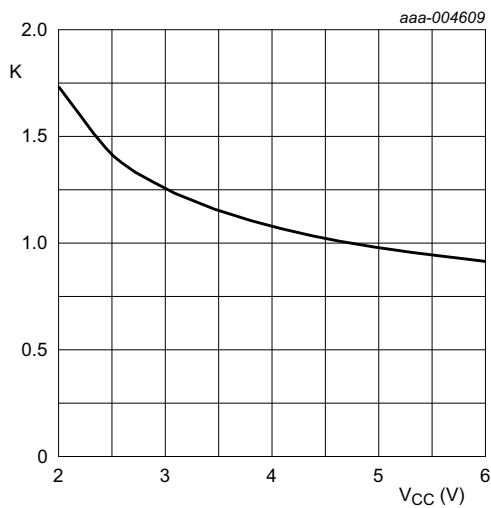
Fig 13. Average additional supply current as a function of V_{CC} for 74HCT14; linear change of V_I between 0.1V_{CC} to 0.9V_{CC}.



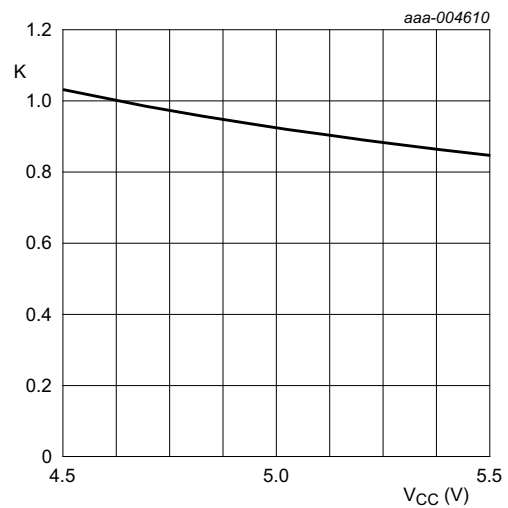
For 74HC14 and 74HCT14: $f = \frac{1}{T} \approx \frac{1}{K \times RC}$

For K-factor see [Figure 15](#)

Fig 14. Relaxation oscillator



K-factor for 74HC14



K-factor for 74HCT14

Fig 15. Typical K-factor for relaxation oscillator

16. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



Fig 16. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



Fig 17. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

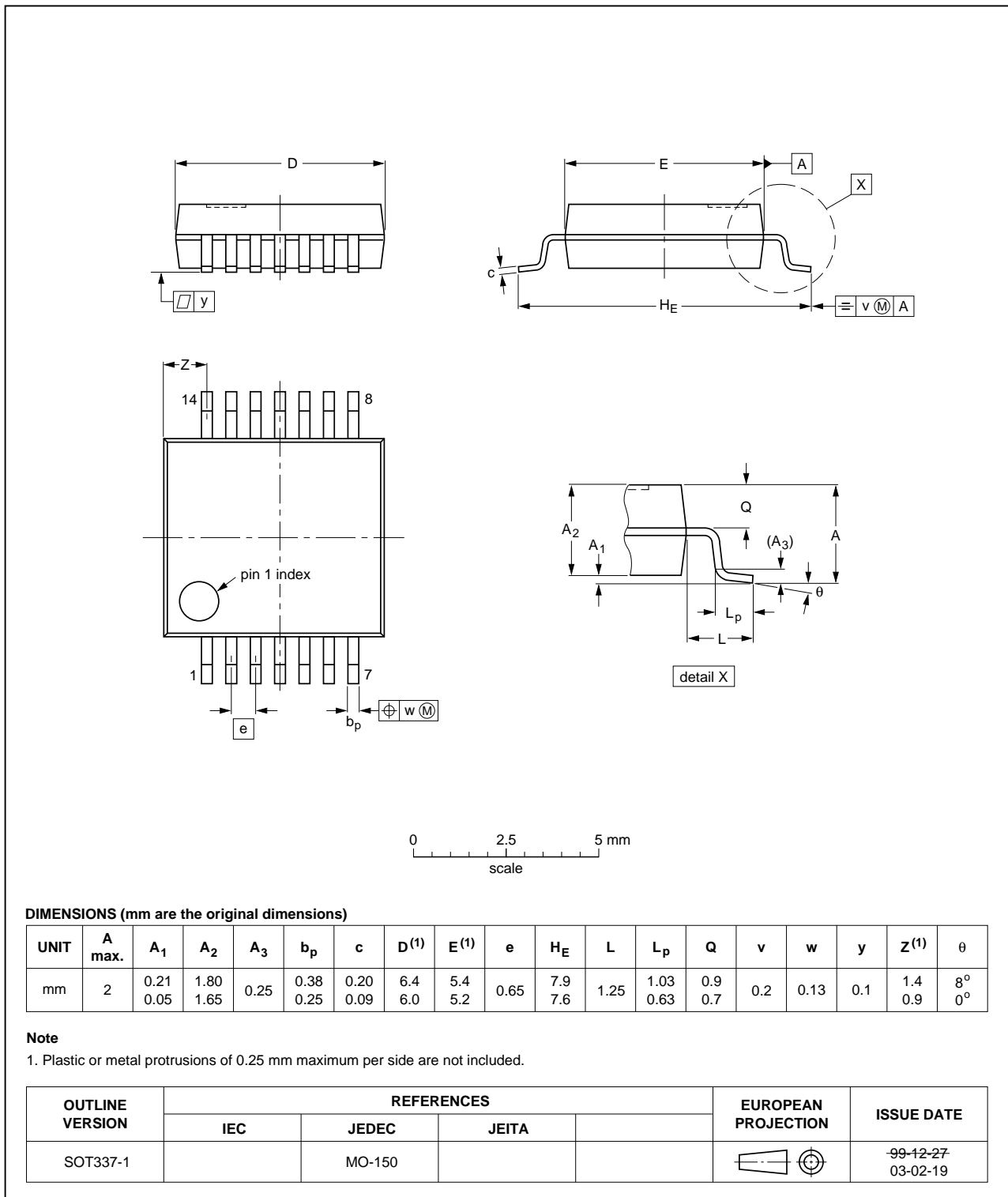


Fig 18. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

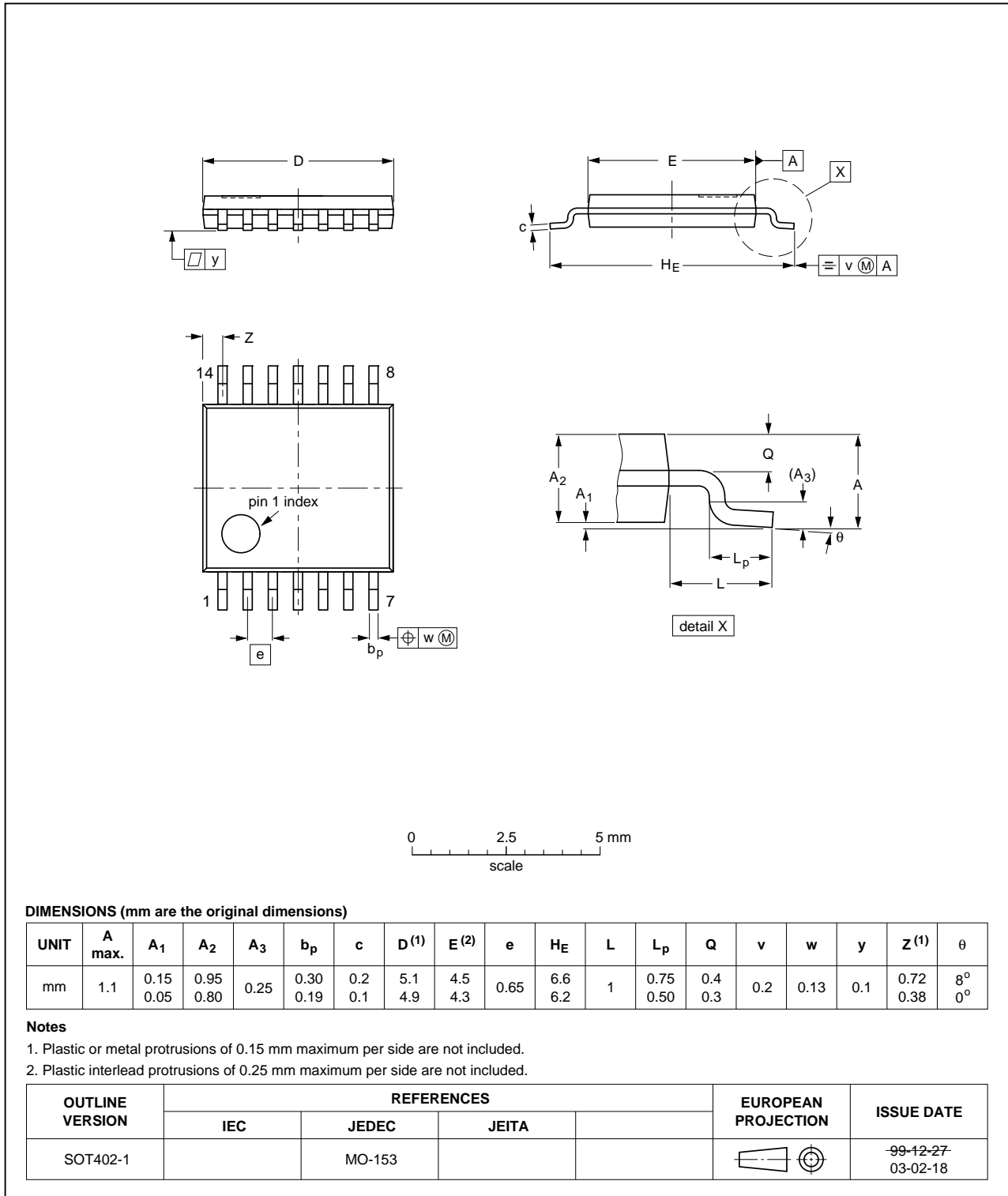


Fig 19. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

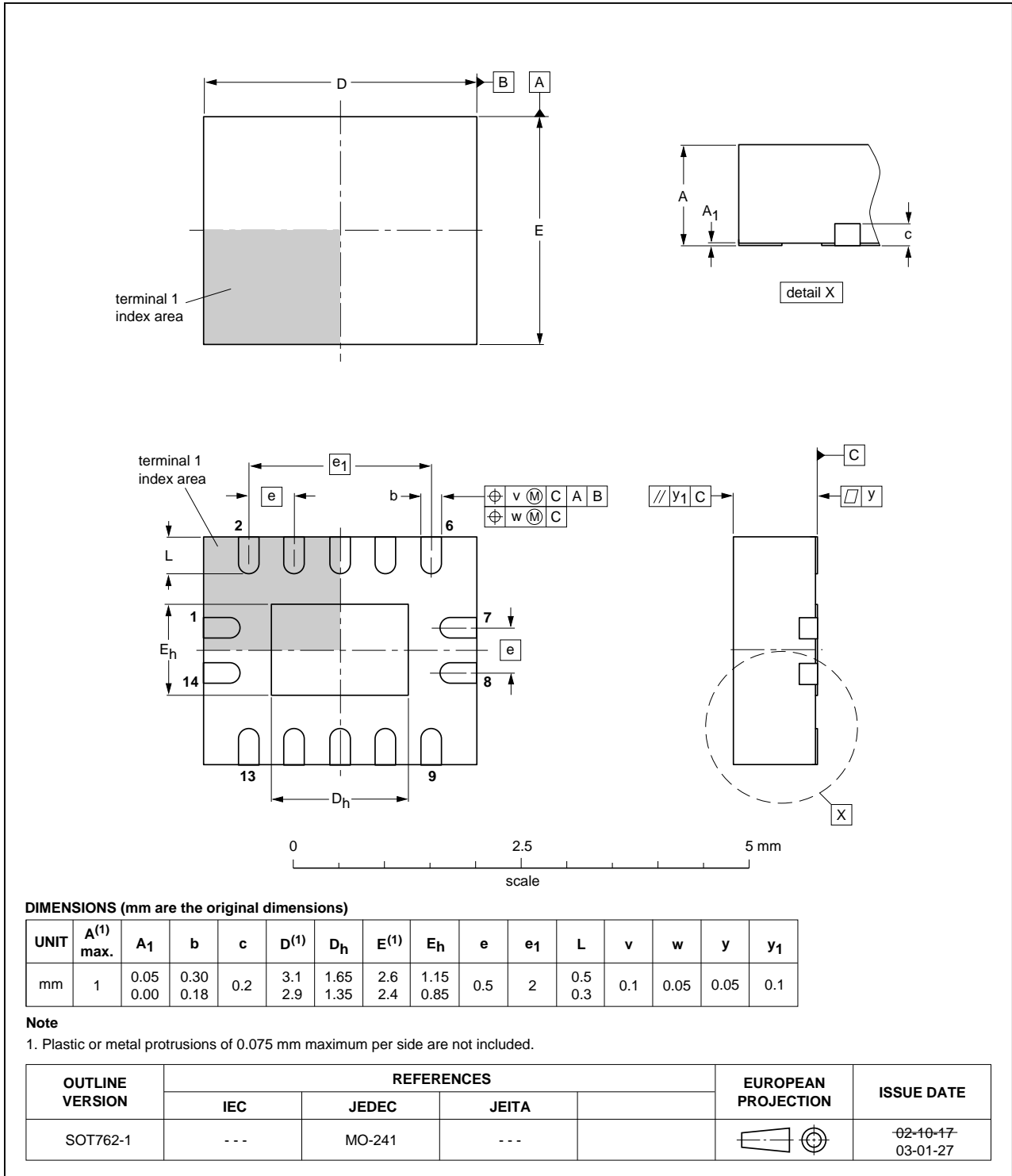


Fig 20. Package outline SOT762-1 (DHVQFN14)

17. Abbreviations

Table 11. Abbreviations

| Acronym | Description |
|---------|--|
| CMOS | Complementary Metal-Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| LSTTL | Low-power Schottky Transistor-Transistor Logic |
| MM | Machine Model |

18. Revision history

Table 12. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|--------------------|---|-----------------------|---------------|--------------------|
| 74HC_HCT14 v.6 | 20120919 | Product data sheet | - | 74HC_HCT14 v.5 |
| Modifications: | <ul style="list-style-type: none"> • Figure 15 added (typical K-factor for relaxation oscillator). | | | |
| 74HC_HCT14 v.5 | 20111219 | Product data sheet | - | 74HC_HCT14 v.4 |
| Modifications: | <ul style="list-style-type: none"> • Legal pages updated. | | | |
| 74HC_HCT14 v.4 | 20110117 | Product data sheet | - | 74HC_HCT14 v.3 |
| 74HC_HCT14 v.3 | 20031030 | Product specification | - | 74HC_HCT14_CNV v.2 |
| 74HC_HCT14_CNV v.2 | 19970826 | Product specification | - | - |

19. Legal information

19.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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